

ABSTRACT

A [[novel]] process of [[for]] lapping a wafer ~~is disclosed, which~~ includes the steps of relieving adhesive stress of an ultraviolet tape attached to a first side of [[a]] the wafer by irradiation of ultraviolet light, maintaining a lapping jig at a usable temperature of the ultraviolet tape to cause a binder applied to the lapping jig to be melted, bonding the first side of the wafer to the lapping jig, and lapping the wafer. ~~Thus, the present invention can provide a process capable of preventing damage to a wafer owing to deformation of an ultraviolet tape. The invention can also simplify an entire process to shorten the time required to complete the process and can minimize damage to a wafer by carrying out a lapping process using an ultraviolet tape as well as a grinding process capable of increasing etching amount of a wafer.~~